

## NC7SZ126

### TinyLogic™ UHS Buffer with 3-STATE Output

#### General Description

The NC7SZ126 is a single buffer with 3-STATE output from Fairchild's Ultra High Speed Series of TinyLogic™. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V range. The inputs and output are high impedance above ground when  $V_{CC}$  is 0V. Inputs tolerate voltages up to 6V independent of  $V_{CC}$  operating voltage. The output tolerates voltages above  $V_{CC}$  in the 3-STATE condition.

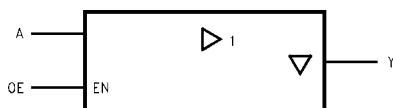
#### Features

- Space saving SOT23 or SC70 5-lead package
- Ultra small MicroPak™ leadless package
- Ultra High Speed;  $t_{PD}$  2.6 ns Typ into 50 pF at 5V  $V_{CC}$
- High Output Drive;  $\pm 24$  mA at 3V  $V_{CC}$
- Broad  $V_{CC}$  Operating Range; 1.65V to 5.5V
- Matches the performance of LCX when operated at 3.3V  $V_{CC}$
- Power down high impedance inputs/output
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

#### Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ126M5X	MA05B	7Z26	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7SZ126P5X	MAA05A	Z26	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ126L6X	MAC06A	FF	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

#### Logic Symbol

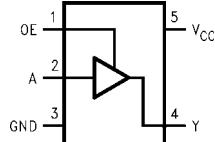


#### Pin Descriptions

Pin Names	Description
A, OE	Inputs
Y	Output
NC	No Connect

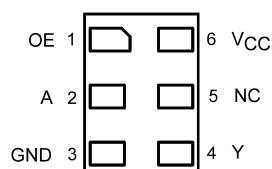
#### Connection Diagrams

Pin Assignments for SC70 and SOT23



(Top View)

Pad Assignments for MicroPak



(Top Thru View)

#### Function Table

Inputs		Output
OE	A	OUT Y
H	L	L
H	H	H
L	X	Z

H = HIGH Logic Level  
L = LOW Logic Level

X = HIGH or LOW Logic Level  
Z = HIGH Impedance State

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**Absolute Maximum Ratings**(Note 1)

Supply Voltage ( $V_{CC}$ )	-0.5V to +6V		Supply Voltage Operating ( $V_{CC}$ )	1.65V to 5.5V
DC Input Voltage ( $V_{IN}$ )	-0.5V to +6V		Supply Voltage Data Retention ( $V_{CC}$ )	1.5V to 5.5V
DC Output Voltage ( $V_{OUT}$ )	-0.5V to +6V		Input Voltage ( $V_{IN}$ )	0V to 5.5V
DC Input Diode Current ( $I_{IK}$ )			Output Voltage ( $V_{OUT}$ )	
@ $V_{IN} < -0.5V$	-50 mA		Active State	0V to $V_{CC}$
@ $V_{IN} > 6V$	+20 mA		3-State	0V to 5.5V
DC Output Diode Current ( $I_{OK}$ )			Operating Temperature ( $T_A$ )	-40°C to +85°C
@ $V_{OUT} < -0.5V$	-50 mA		Input Rise and Fall Time ( $t_r, t_f$ )	
@ $V_{OUT} > 6V, V_{CC} = GND$	+20 mA		$V_{CC} = 1.8V, 2.5V \pm 0.2V$	0 ns/V to 20 ns/V
DC Output Current ( $I_{OUT}$ )	±50 mA		$V_{CC} = 3.3V \pm 0.3V$	0 ns/V to 10 ns/V
DC $V_{CC}/GND$ Current ( $I_{CC}/I_{GND}$ )	±50 mA		$V_{CC} = 5.0V \pm 0.5V$	0 ns/V to 5 ns/V
Storage Temperature ( $T_{STG}$ )	-65°C to +150°C		Thermal Resistance ( $\theta_{JA}$ )	
Junction Temperature under Bias ( $T_J$ )	150°C		SOT23-5	300°C/W
Junction Lead Temperature ( $T_L$ ); (Soldering, 10 seconds)	260°C		SC70-5	425°C/W
Power Dissipation ( $P_D$ ) @+85°C				
SOT23-5	200 mW			
SC70-5	150 mW			

**Recommended Operating Conditions** (Note 2)

Supply Voltage Operating ( $V_{CC}$ )	1.65V to 5.5V
Supply Voltage Data Retention ( $V_{CC}$ )	1.5V to 5.5V
Input Voltage ( $V_{IN}$ )	0V to 5.5V
Output Voltage ( $V_{OUT}$ )	
Active State	0V to $V_{CC}$
3-State	0V to 5.5V
Operating Temperature ( $T_A$ )	-40°C to +85°C
Input Rise and Fall Time ( $t_r, t_f$ )	
$V_{CC} = 1.8V, 2.5V \pm 0.2V$	0 ns/V to 20 ns/V
$V_{CC} = 3.3V \pm 0.3V$	0 ns/V to 10 ns/V
$V_{CC} = 5.0V \pm 0.5V$	0 ns/V to 5 ns/V
Thermal Resistance ( $\theta_{JA}$ )	
SOT23-5	300°C/W
SC70-5	425°C/W

**Note 1:** Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. The datasheet specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside datasheet specifications.

**Note 2:** Unused inputs must be held HIGH or LOW. They may not float.

**DC Electrical Characteristics**

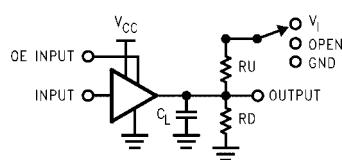
Symbol	Parameter	$V_{CC}$ (V)	$T_A = +25^\circ C$			Unit	Conditions
			Min	Typ	Max		
$V_{IH}$	HIGH Level Input Voltage	1.65 to 1.95 2.3 to 5.5	0.75 $V_{CC}$ 0.7 $V_{CC}$			0.75 $V_{CC}$ 0.7 $V_{CC}$	V
$V_{IL}$	LOW Level Input Voltage	1.65 to 1.95 2.3 to 5.5		0.25 $V_{CC}$ 0.3 $V_{CC}$		0.25 $V_{CC}$ 0.3 $V_{CC}$	V
$V_{OH}$	HIGH Level Output Voltage	1.65	1.55	1.65		1.55	
		1.8	1.7	1.8		1.7	
		2.3	2.2	2.3		2.2	
		3.0	2.9	3.0		2.9	
		4.5	4.4	4.5		4.4	
	LOW Level Output Voltage	1.65	1.29	1.52		1.29	
		2.3	1.9	2.15		1.9	
		3.0	2.4	2.80		2.4	
		3.0	2.3	2.68		2.3	
		4.5	3.8	4.20		3.8	
$V_{OL}$	LOW Level Output Voltage	1.65	0.0	0.1		0.1	
		1.8	0.0	0.1		0.1	
		2.3	0.0	0.1		0.1	
		3.0	0.0	0.1		0.1	
		4.5	0.0	0.1		0.1	
	3-STATE Output Leakage	1.65	0.08	0.24		0.24	
		2.3	0.10	0.3		0.3	
		3.0	0.15	0.4		0.4	
		3.0	0.22	0.55		0.55	
		4.5	0.22	0.55		0.55	
$I_{IN}$	Input Leakage Current	0 to 5.5		±1		±10	μA
$I_{OZ}$	3-STATE Output Leakage	0 to 5.5		±1		±10	μA
$I_{OFF}$	Power Off Leakage Current	0.0		1		10	μA
$I_{CC}$	Quiescent Supply Current	1.65 to 5.5		2.0		20	μA

## AC Electrical Characteristics

Symbol	Parameter	$V_{CC}$ (V)	$T_A = +25^\circ C$			Units	Conditions	Fig. No.
			Min	Typ	Max			
$t_{PLH}$	Propagation Delay	1.65	2.0	6.4	13.2	ns	$C_L = 15 \text{ pF}$ , $RD = 1 \text{ M}\Omega$ $S_1 = \text{OPEN}$	Figures 1, 3
		1.8	2	5.3	11			
		$2.5 \pm 0.2$	0.8	3.4	7.5			
		$3.3 \pm 0.3$	0.5	2.5	5.2			
		$5.0 \pm 0.5$	0.5	2.1	4.5			
$t_{PHL}$	Propagation Delay	$3.3 \pm 0.3$	1.5	3.2	5.7	ns	$C_L = 50 \text{ pF}$ , $RD = 500\Omega$ $S_1 = \text{OPEN}$	Figures 1, 3
		$5.0 \pm 0.5$	0.8	2.6	5.0			
$t_{PZL}$	Output Enable Time	1.65	2.0	8.4	15.0	ns	$C_L = 50 \text{ pF}$ , $RD = 500\Omega$ , $RU = 500\Omega$ $S_1 = \text{GND}$ for $t_{PZH}$ $S_1 = V_I$ for $t_{PZL}$ $V_I = 2 \times V_{CC}$	Figures 1, 3
		1.8	2.0	6.1	11.5			
		$2.5 \pm 0.2$	1.5	3.8	8.0			
		$3.3 \pm 0.3$	1.5	3.2	5.7			
		$5.0 \pm 0.5$	0.8	2.3	5.0			
$t_{PHZ}$	Output Disable Time	1.65	2.0	6.5	13.2	ns	$C_L = 50 \text{ pF}$ , $RD = 500\Omega$ , $RU = 500\Omega$ $S_1 = \text{GND}$ for $t_{PHZ}$ $S_1 = V_I$ for $t_{PLZ}$ $V_I = 2 \times V_{CC}$	Figures 1, 3
		1.8	2.0	5.6	11			
		$2.5 \pm 0.2$	1.0	4.0	8.0			
		$3.3 \pm 0.3$	1.0	3.5	5.7			
		$5.0 \pm 0.5$	0.5	2.5	4.7			
$C_{IN}$	Input Capacitance	0	4			pF		
$C_{OUT}$	Output Capacitance	0	8					
$C_{PD}$	Power Dissipation Capacitance	3.3 5.0	17 24			pF	(Note 3)	Figure 2

Note 3:  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption ( $I_{CCD}$ ) at no output loading and operating at 50% duty cycle. (See Figure 2.)  $C_{PD}$  is related to  $I_{CCD}$  dynamic operating current by the expression:  
 $I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC} \text{ static}).$

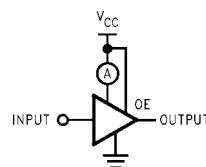
## AC Loading and Waveforms



$C_L$  includes load and stray capacitance

Input PRR = 1.0 MHz,  $t_W = 500$  ns

FIGURE 1. AC Test Circuit



Input = AC Waveform;  $t_f = t_r = 1.8$  ns;

PRR = 10 MHz; Duty Cycle = 50%

FIGURE 2.  $I_{CCD}$  Test Circuit

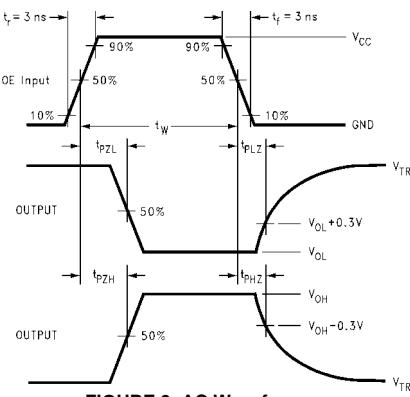
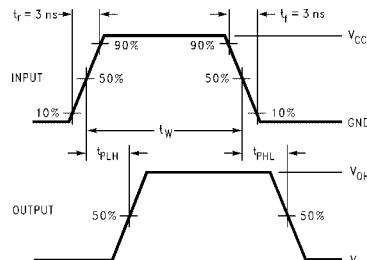


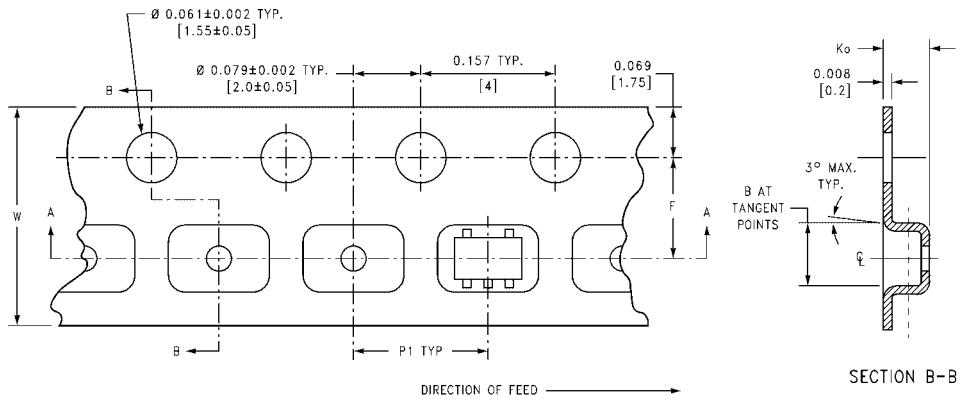
FIGURE 3. AC Waveforms

## Tape and Reel Specification

TAPE FORMAT for SC70 and SOT23

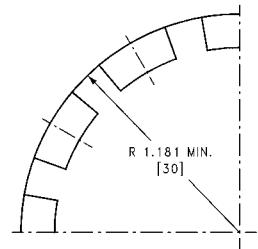
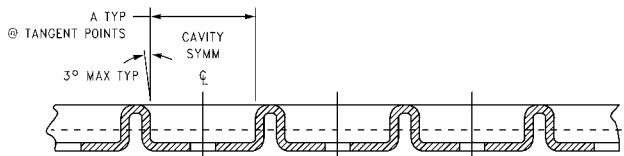
Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

### TAPE DIMENSIONS inches (millimeters)



DIRECTION OF FEED →

SECTION B-B



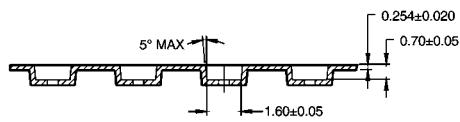
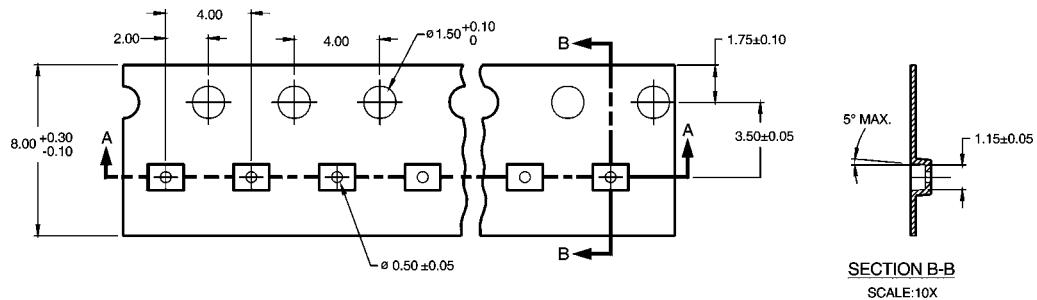
BEND RADIUS NOT TO SCALE

Package	Tape Size	DIM A	DIM B	DIM F	DIM K <sub>o</sub>	DIM P1	DIM W
SC70-5	8 mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)
SOT23-5	8 mm	0.130 (3.3)	0.130 (3.3)	0.138 ± 0.002 (3.5 ± 0.05)	0.055 ± 0.004 (1.4 ± 0.11)	0.157 (4)	0.315 ± 0.012 (8 ± 0.3)

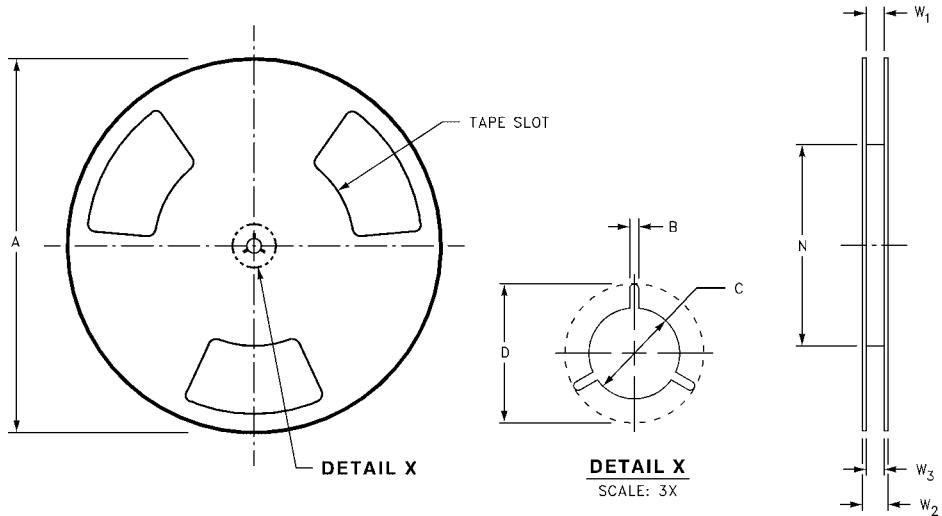
## Tape and Reel Specification (Continued)

### TAPE FORMAT for MircoPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

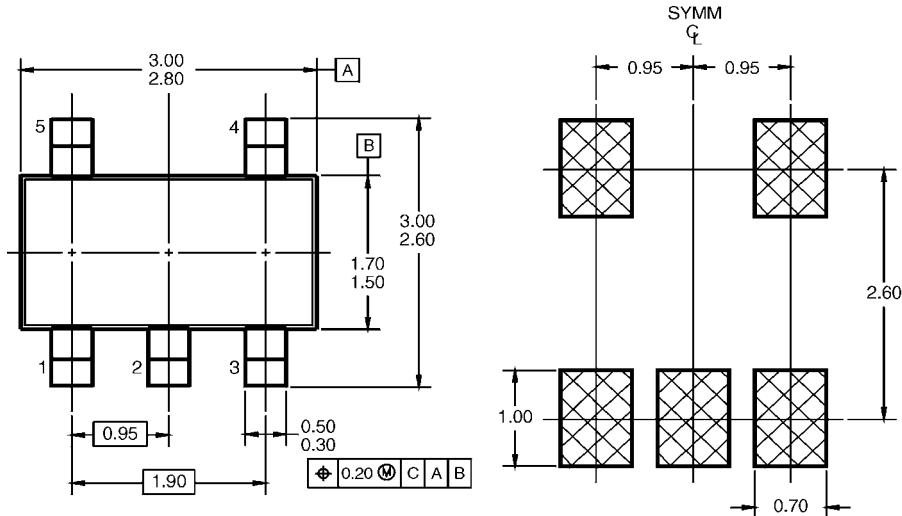


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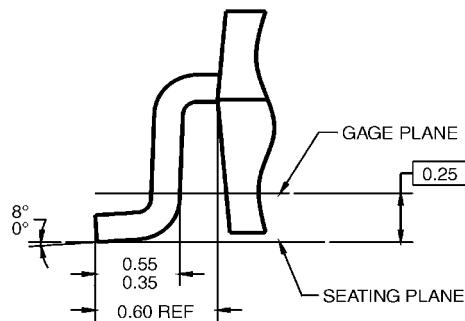
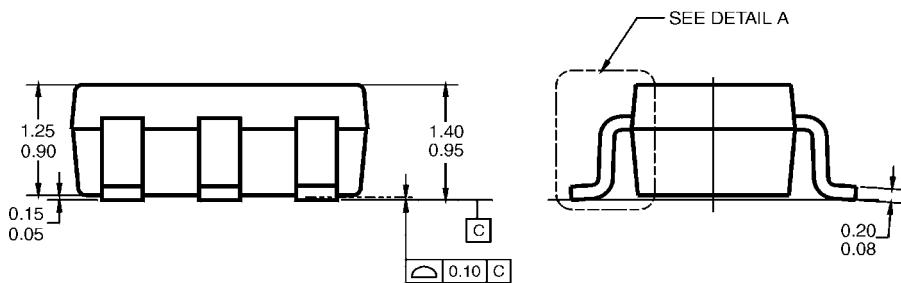
**Tape and Reel Specification** (Continued)  
REEL DIMENSIONS inches (millimeters)

Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	$0.331 + 0.059/-0.000$ (8.40 + 1.50/-0.00)	0.567 (14.40)	$W_1 + 0.078/-0.039$ ( $W_1 + 2.00/-1.00$ )

**Physical Dimensions** inches (millimeters) unless otherwise noted



LAND PATTERN RECOMMENDATION



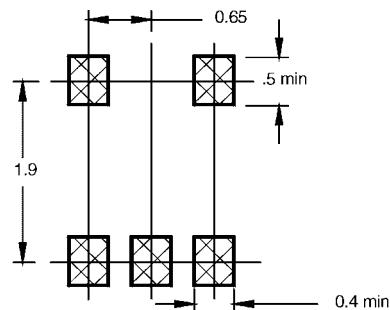
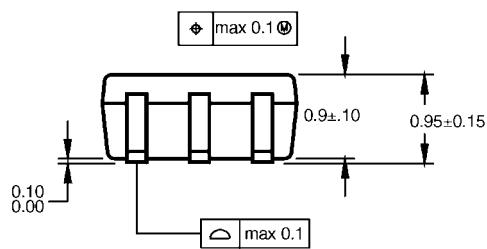
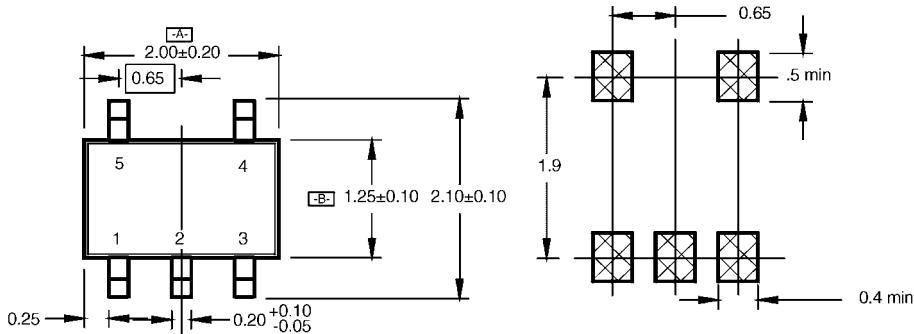
NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE CONFORMS TO JEDEC  
 MO-178, ISSUE B, VARIATION AA,  
 DATED JANUARY 1999.  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.

MA05BRevC

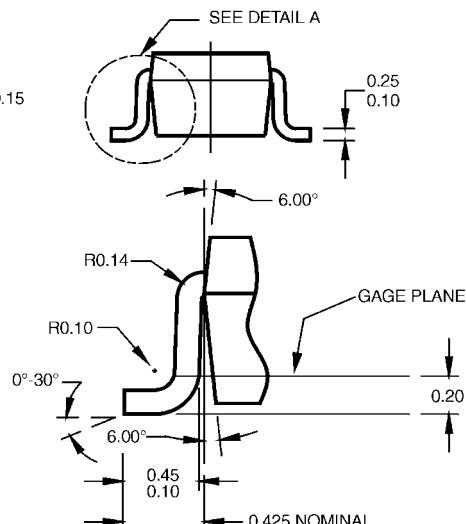
5-Lead SOT23, JEDEC MO-178, 1.6mm  
 Package Number MA05B

NC7SZ126

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DETAIL A

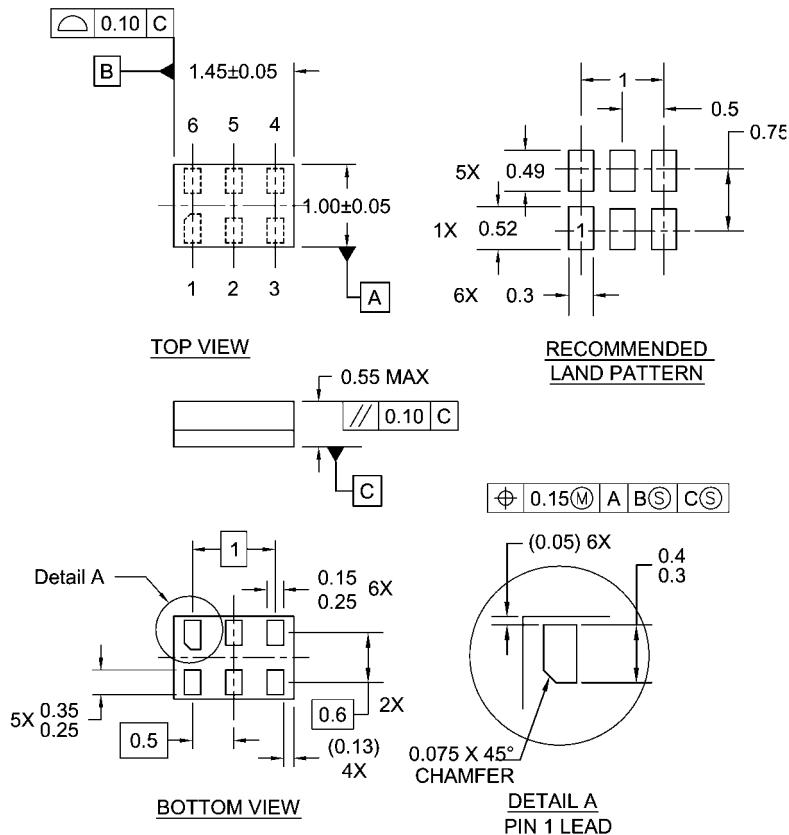
NOTES:

- A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88A.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
- C. DIMENSIONS ARE IN MILLIMETERS.

MAA05ARevC

5-Lead SC70, EIAJ SC-88a, 1.25mm Wide  
Package Number MAA05A

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

6-Lead MicroPak, 1.0mm Wide  
Package Number MAC06A

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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